

APPROVAL SHEET

AOT MODEL NAME	4014PCT
AOT PART NUMBER	4014C-B001
CUSTOMER NAME	General
DATE	2021/Sep
VERSION	01

MAKER		CUST	OMER		
Prepared	Checked	Approved			
Yo.Chen					

AOT Headquarters No. 13, Gongye 5th. Road, Hsinchu Industrial Park, Hukou Shiang, Hsinchu Hsien 303, Taiwan, R.O.C. TEL: +886-3-597-6988 / FAX: +886-3-598-7392



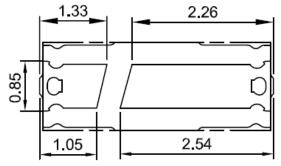
Date	Revision	Page	Version
2021-09-14	Initiate Document	16	1



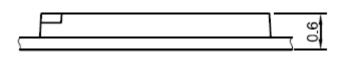
Type Number:4014C-B001

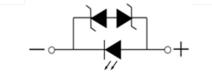
Unit: mm, Tolerance: ± 0.2 mm

Bottom View

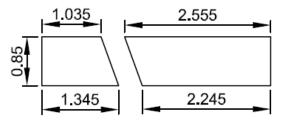


Front View





Recommended soldering pad design



ltem	Materials
Package	Heat-Resistant Polymer
Encapsulating Material	Silicone Resin
Electrode	Ag Plating Copper Alloy

- Single blue chip.
- High brightness SMD.
- Compact package outline (LxWxH) of 4.0 mm x 1.4 mm x 0.6 mm.
- Compatible with reflow soldering.
- Complies with RoHS Directive.



AOT Reading Standards						
Item	Symbol	Condition	Min	Тур	Max	Unit
Forward Voltage	VF	I _F = 20mA	2.7	-	2.9	V
Luminous Flux	φv	I⊧ = 20mA	35	-	39	mW
Thermal Resistance	R _{thj-s}	-	13 (T _s =25°C)	16 (T _s =25°C)		°C/W

* Tolerance of measurements of the Forward Voltage is \pm 0.05 V.

* Tolerance of measurements of the Luminous Flux is ± 7%.

Absolute Maximum Ratings (Ts=25°C)

Item	Symbol	Maximum Value	Unit
Forward Current	I _F	30	mA
Peak Pulse Forward Current	I _{FP}	90	mA
LED Junction Temperature.	Tj	125	°C
Operating Temperature.	T _{opr}	-35 ~ +85	°C
Storage Temperature.	T _{stg}	-40 ~ +100	°C
Power Dissipation	PD	87	mW
Soldering Temperature	T _{sld}	Reflow Soldering 260°C,10sec	
Forward Voltage at Low Current	V _{F2}	>1.9 (@1uA)	

* IFP Conditions : Pulse Width \leq 10msec, and duty \leq 1/10

* Max condition is not guarantee for life time



Rank	Condition	VF(V)
S2	T _A =25°C	2.7 ~ 2.8
S3	I _F =20mA	2.8 ~ 2.9

Group Definition of Brightness

Rank	Condition	Luminous Flux(mW)
A35	T _A =25°C I⊧=20mA	35 ~ 36
A36		36 ~ 37
A37		37 ~ 38
A38		38 ~ 39

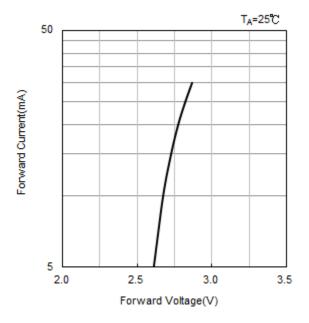
*A shipment shall consist of LEDs in a combination of above ranks.

*The percentage of each rank in the shipment shall be determined by AOT.

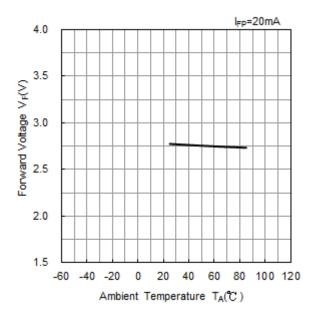
*The ranking information of LEDs can be found on the reel label.



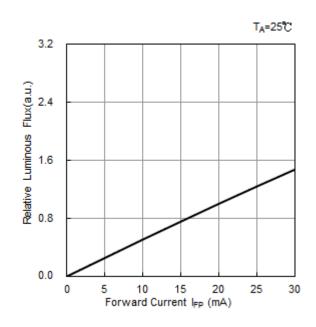
Forward Voltage vs. Forward Current



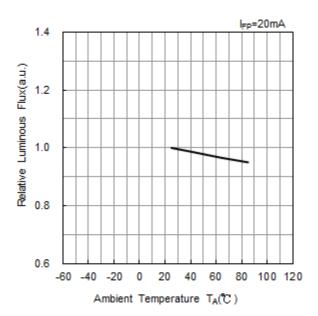
Ambient Temperature vs. Forward Voltage



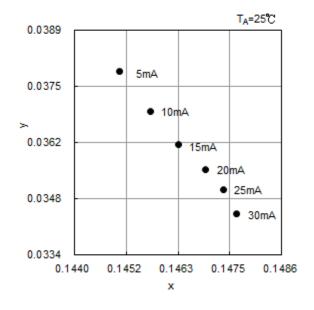
Forward Current vs. Relative Luminous Flux



Ambient Temperature vs. Relative Luminous

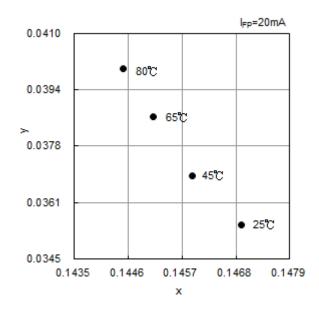




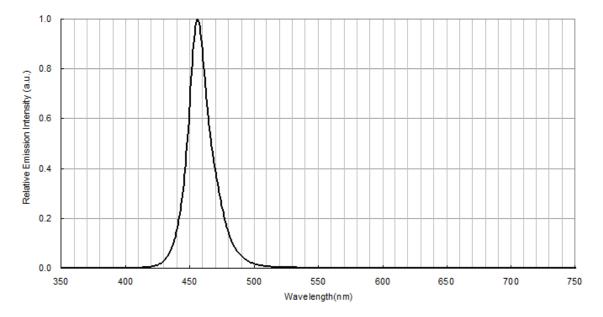


Forward Current vs.Chromaticity Coordinate

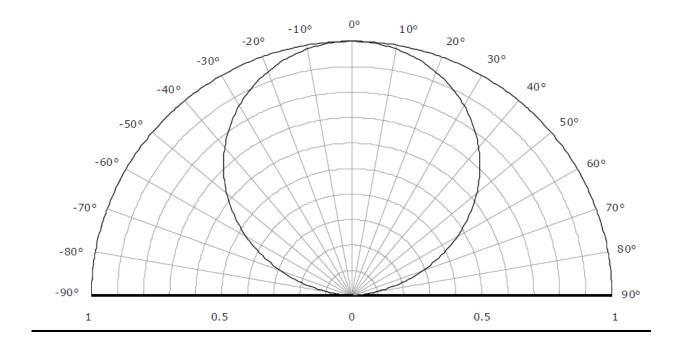
Ambient Temperature vs. Chromaticity Coordinate







Radiation Pattern(T_A=25°C, I_{FP}=20mA)





Recommended Reflow Soldering Conditions

Surface Mounting Condition

In automatic mounting of the SMD LEDs on printed circuit boards, any bending, expanding and pulling forces or shock against the SMD LEDs should be kept min. to prevent them from electrical failures and mechanical damages of the devices.

Soldering Reflow

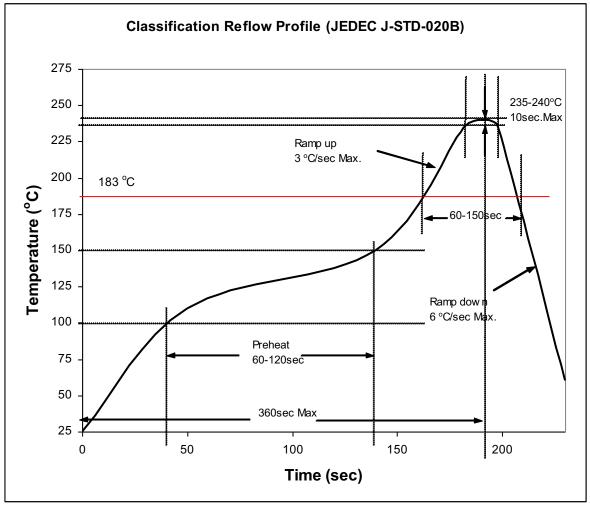
-Soldering of the SMD LEDs should conform to the soldering condition in the individual specifications. -SMD LEDs are designed for Reflow Soldering.

-In the reflow soldering, too high temperature and too large temperature gradient such as rapid heating/cooling may cause electrical & optical failures and damages of the devices.

-AOT cannot guarantee the LEDs after they have been assembled using the solder dipping method.

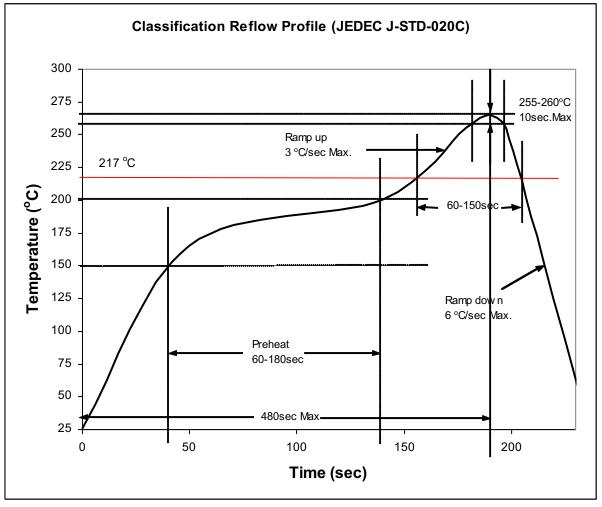
1) Lead Solder





2) Lead-free Solder





3) Manual Soldering Conditions

- Lead Solder

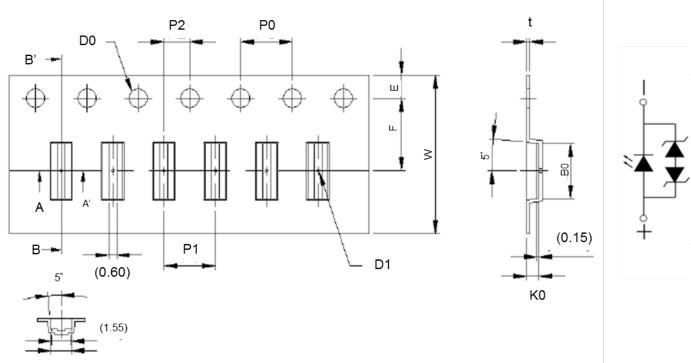
Max. 300 °C for Max. 3sec, and only one time.

- Lead-free Solder

Max. 350 °C for Max. 3sec, and only one time.

- There is possibility that the brightness of LEDs is decreased, which is influenced by heat or ambient atmosphere during reflow. It is recommended to use the nitrogen reflow method.
- After LEDs have been soldered, repair should not be done. As repair is unavoidable, a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will be damaged by repairing or not.
- Reflow soldering should not be done more than two times.

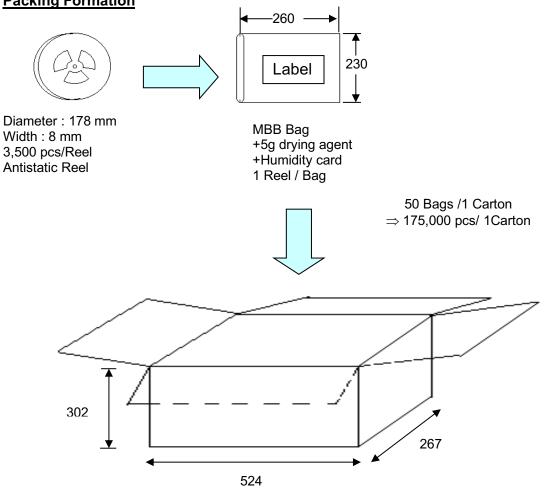




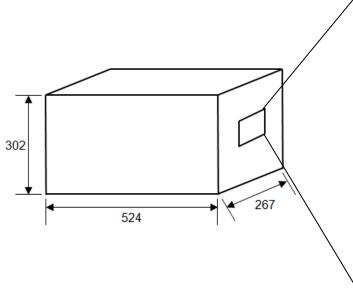
	_
Λ	\sim
н	U

ltem	Spec.	Tolerance(mm)	ltem	Spec.	Tolerance(mm)
W	12.00	±0.20	P2	2.00	±0.05
E	1.75	±0.10	t	0.23	±0.05
F	5.50	±0.10	A0	1.55	±0.05
D0	1.50	±0.10,-0	B0	4.20	±0.05
D1	1.00	±0.10	K0	0.95	±0.05
P0	4.00	±0.10	α	Max 5°	
P1	4.00	±0.10			





Package Outlook



	Solid-State Light. Done Right. Advanced Optoelectronic Technology Inc.			
	Customer			
	PO No.			
	Part No.			
	Quantity			
	Packing Date			
	Carton No.			
	Ship No.			
	QC Check	The state of the s		
\setminus	備註			



		SAP. No.
SMD LED		
Part Numbe	er : XXXXX-XXXX	
Brightness	: A	
CIE	: B	
VF	: C	
Quantity	: nn ea	
Serial No	: SM0yymmddxxxx	ANSS PASS PASS
		(* ROHS »)
Cust. PN.	: XXXXX-XXXX	STY ON STO
00001110		- 3244 90

A : lv value. B : CIE value noted C : Vf value. nn : Quantity of LED

SM0yymmddxxx : yy : year, mm : month, dd : day, xxxx : reel no.

*Reel Label to fill in practice data of all LED characteristic



No.	Test Item	Standard Test	Test	Note	Number of
		Method	Conditions		Damaged
1	Room Temp. Life Test	Internal Ref.	T _A =25 °C,I⊧=20mA	1000 hr	0/20
2	High Temp. Operation	JESD22-A108	T _A =65°C,I⊧=20mA	1000 hr	0/20
3	High Temp. Operation	JESD22-A108	T _A =85°C,I⊧=20mA	1000 hr	0/20
4	High Temp. Storage	JESD22-A103	T _A =100°C	1000 hr	0/20
5	Low Temp. Operation	JESD22-A108	T _A =-40°C,I _F =20mA	1000 hr	0/20
6	High Temp. and High Humidity Operation	JESD22-A119	60°C 90%RH,I⊧=20mA	1000 hr	0/20
7	Temperature and humidity cycle test	IEC68-2-38	25°C ~65°C ~-10°C,90% RH 24hr per cycle	10 cycle	0/20
8	Thermal Cycling Test	JESD22-A106	-40°C ~ 100°C ,30min Transform time 5min	300 cycles	0/50

Criteria for Judging Damage

ltom	Symbol	Toot Conditions	Criteria for Judgement		
ltem		Test Conditions	Min.	Max.	
Forward Voltage	VF	I⊧=20mA	-	*U.S.L×1.1	
Luminous Flux	φv	I⊧=20mA	*L.S.L×0.7	-	

* U.S.L: Upper Standard Level

* L.S.L: Lower Standard Level



(1) Moisture Proof Package

The moisture proof package should be used to prevent moisture in the package as the moisture may Cause damage to optical characteristics of the LEDs.

The aluminum bag with zipper is used for moisture proof package. And, the moisture absorbent Material, Silica gel, is inserted into aluminum bag.

(2) Storage:

Storage Conditions

Before opening the package:

The LEDs should be kept at 30°C or less than 90%RH or less. The LEDs should be used within a year. When storing the LEDs, moisture proof packaging with absorbent material is recommended. After opening the package:

After open the package, the LED should be kept at 30°C, 60%RH or less. The LED should be soldered within 168 hours (7 days) after opening the package. If unused LEDs remain, it should be stored in moisture proof condition.

(3) Heat Generation

Thermal design of the end products is of paramount importance. The heat generation must be taken into design consideration when using the LED. The coefficient of the temperature increase per input electric power is affected by the thermal resistance of the circuit board and density of LED placement on the board, as well as other components.

(4) Static Electricity

Static electricity or surge voltage damages the LEDs. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LEDs. When inspecting the final products in which LEDs were assembled, it is recommended to check whether the assembled LEDs are damaged by static electricity or not. It is easy to find static-damaged LEDs by a light-on test or a Vf test at a lower current. (Below 1mA is recommended). Criteria: $V_f > 1.9V$ at $I_f = 1uA$

(5) Cleaning

Use isopropyl alcohol as a solvent for cleaning the LEDs. The other solvent may dissolve the LEDs package and the epoxy.

Ultrasonic cleaning should not be done.

(6) Electrostatic Discharge (ESD)

The products are sensitive to static electricity or surge voltage, An ESD event may damage its die or reduce its reliability performance. When handling the products, measures against electro static discharge, including the followings, are strongly recommended.

Eliminating the charge; Wrist strap, ESD footwear and garments, ESD floors Grounding the equipment and tools at workstation

4014C-B001



ESD table / shelf mat (conductive materials)

Proper grounding techniques are required for all devices, equipment and machinery used in the assembly of the products, Also note that surge protection should be considered in the design of customer products.

If tools or equipment contain insulating materials, such as glass or plastic, proper measures against electro static discharge, including the followings are strongly recommended.

Dissipating the charge with conductive materials

Preventing the charge generation with moisture

Neutralizing the charge with ionizer

(7) Others

When using the LEDs, it must care that the reverse voltage will not exceed the absolute maximum rating. The LED light is enough to injure human eyes, so it should avoid looking at LED light directly.

NOTE.

All the information published is considered to be reliable. However, AOT does not assume any liability arising out of the application or use of any product described herein.

AOT reserves the right to make changes at any time without notice to any products in order to improve reliability, function or design.

AOT products are not authorized for use as critical components in life support devices or systems without the express written approval from the managing director of AOT.